Infineon Technologies - SAF-XC888CLM-8FFA 5V AC Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	XC800
Core Size	8-Bit
Speed	24MHz
Connectivity	CANbus, LINbus, SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	48
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1.75K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	PG-TQFP-64
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/saf-xc888clm-8ffa-5v-ac

2.2 Logic Symbol

The logic symbols of the XC886/888 are shown in **Figure 3**.

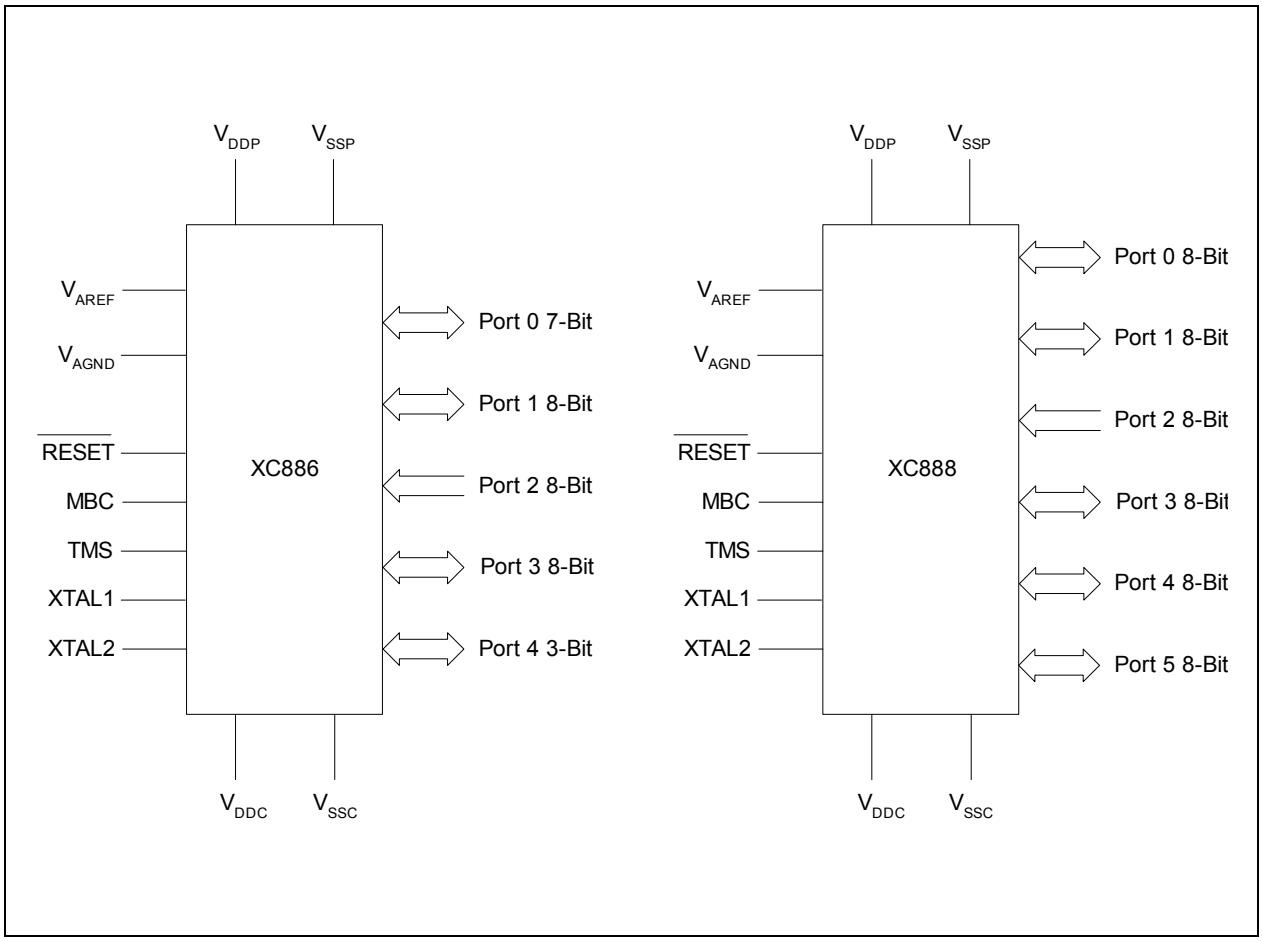


Figure 3 XC886/888 Logic Symbol

- Overwrite the contents of PAGE with the contents of STx, ignoring the value written to the bit positions of PAGE
  (this is done at the end of the interrupt routine to restore the previous page setting before the interrupt occurred)

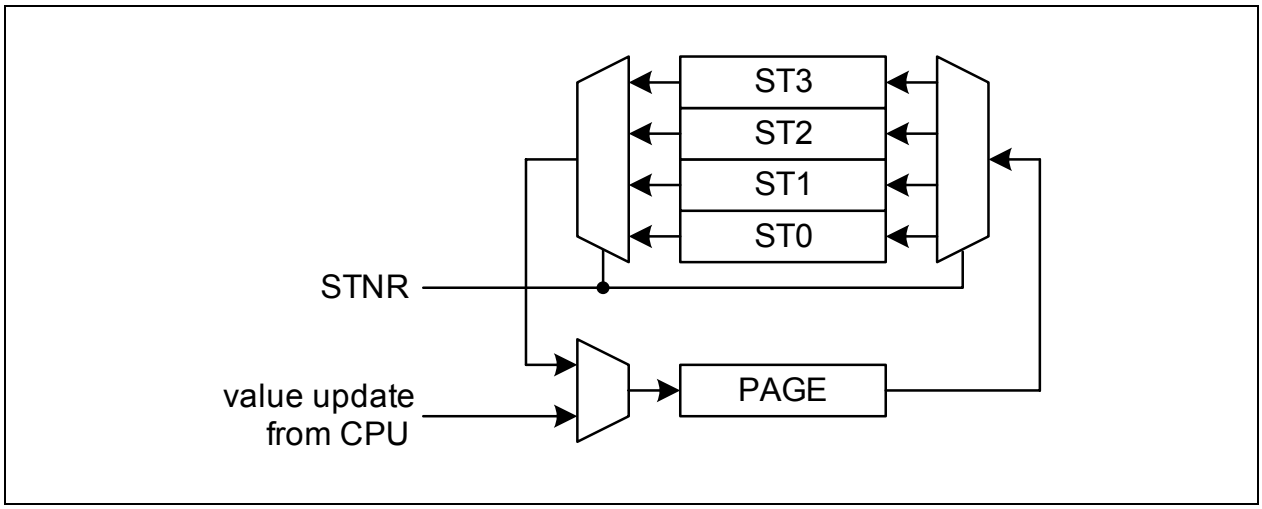


Figure 10 Storage Elements for Paging

With this mechanism, a certain number of interrupt routines (or other routines) can perform page changes without reading and storing the previously used page information. The use of only write operations makes the system simpler and faster. Consequently, this mechanism significantly improves the performance of short interrupt routines.

The XC886/888 supports local address extension for:

- Parallel Ports
- Analog-to-Digital Converter (ADC)
- Capture/Compare Unit 6 (CCU6)
- System Control Registers

Field	Bits	Type	Description
OP	[7:6]	w	**Operation** 0X Manual page mode. The value of STNR is ignored and PAGE is directly written. 10 New page programming with automatic page saving. The value written to the bit positions of PAGE is stored. In parallel, the previous contents of PAGE are saved in the storage bit field STx indicated by STNR. 11 Automatic restore page action. The value written to the bit positions PAGE is ignored and instead, PAGE is overwritten by the contents of the storage bit field STx indicated by STNR.
0	3	r	**Reserved** Returns 0 if read; should be written with 0.

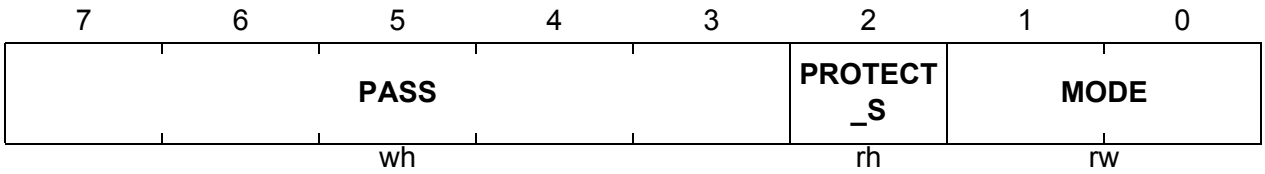
3.2.3 Bit Protection Scheme

The bit protection scheme prevents direct software writing of selected bits (i.e., protected bits) using the PASSWD register. When the bit field MODE is 11_B, writing 10011_B to the bit field PASS opens access to writing of all protected bits, and writing 10101_B to the bit field PASS closes access to writing of all protected bits. In both cases, the value of the bit field MODE is not changed even if PASSWD register is written with 98_H or $A8_H$. It can only be changed when bit field PASS is written with 11000_B, for example, writing $D0_H$ to PASSWD register disables the bit protection scheme.

Note that access is opened for maximum 32 CCLKs if the “close access” password is not written. If “open access” password is written again before the end of 32 CCLK cycles, there will be a recount of 32 CCLK cycles. The protected bits include the N- and K-Divider bits, NDIV and KDIV; the Watchdog Timer enable bit, WDTEN; and the power-down and slow-down enable bits, PD and SD.

3.2.3.1 Password Register

PASSWD
Password Register **Reset Value: 07_H**



Field	Bits	Type	Description
MODE	[1:0]	rw	**Bit Protection Scheme Control Bits** 00 Scheme disabled - direct access to the protected bits is allowed. 11 Scheme enabled - the bit field PASS has to be written with the passwords to open and close the access to protected bits. (default) Others:Scheme Enabled. These two bits cannot be written directly. To change the value between 11_B and 00_B, the bit field PASS must be written with 11000_B; only then, will the MODE[1:0] be registered.
PROTECT_S	2	rh	**Bit Protection Signal Status Bit** This bit shows the status of the protection. 0 Software is able to write to all protected bits. 1 Software is unable to write to any protected bits.
PASS	[7:3]	wh	**Password Bits** The Bit Protection Scheme only recognizes three patterns. 11000_B Enables writing of the bit field MODE. 10011_B Opens access to writing of all protected bits. 10101_B Closes access to writing of all protected bits

3.2.4 XC886/888 Register Overview

The SFRs of the XC886/888 are organized into groups according to their functional units. The contents (bits) of the SFRs are summarized in **Chapter 3.2.4.1** to **Chapter 3.2.4.14**.

Note: The addresses of the bitaddressable SFRs appear in bold typeface.

3.2.4.1 CPU Registers

The CPU SFRs can be accessed in both the standard and mapped memory areas (RMAP = 0 or 1).

Table 5 CPU Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0 or 1										
81_H	**SP** **Reset: 07_H** Stack Pointer Register	Bit Field	SP							
		Type	rw							
82_H	**DPL** **Reset: 00_H** Data Pointer Register Low	Bit Field	DPL7	DPL6	DPL5	DPL4	DPL3	DPL2	DPL1	DPL0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
83_H	**DPH** **Reset: 00_H** Data Pointer Register High	Bit Field	DPH7	DPH6	DPH5	DPH4	DPH3	DPH2	DPH1	DPH0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
87_H	**PCON** **Reset: 00_H** Power Control Register	Bit Field	SMOD	0			GF1	GF0	0	IDLE
		Type	rw	r			rw	rw	r	rw
88_H	**TCON** **Reset: 00_H** Timer Control Register	Bit Field	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0
		Type	rwh	rw	rwh	rw	rwh	rw	rwh	rw
89_H	**TMOD** **Reset: 00_H** Timer Mode Register	Bit Field	GATE 1	T1S	T1M		GATE 0	T0S	T0M	
		Type	rw	rw	rw		rw	rw	rw	
$8A_H$	**TL0** **Reset: 00_H** Timer 0 Register Low	Bit Field	VAL							
		Type	rwh							
$8B_H$	**TL1** **Reset: 00_H** Timer 1 Register Low	Bit Field	VAL							
		Type	rwh							
$8C_H$	**TH0** **Reset: 00_H** Timer 0 Register High	Bit Field	VAL							
		Type	rwh							
$8D_H$	**TH1** **Reset: 00_H** Timer 1 Register High	Bit Field	VAL							
		Type	rwh							
98_H	**SCON** **Reset: 00_H** Serial Channel Control Register	Bit Field	SM0	SM1	SM2	REN	TB8	RB8	TI	RI
		Type	rw	rw	rw	rw	rw	rwh	rwh	rwh
99_H	**SBUF** **Reset: 00_H** Serial Data Buffer Register	Bit Field	VAL							
		Type	rwh							
$A2_H$	**EO** **Reset: 00_H** Extended Operation Register	Bit Field	0			TRAP_EN	0			DPSEL0
		Type	r			rw	r			rw

Table 6 MDU Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
$B3_H$	**MR1** **Reset: 00_H** MDU Result Register 1	Bit Field	DATA							
		Type	rh							
$B4_H$	**MD2** **Reset: 00_H** MDU Operand Register 2	Bit Field	DATA							
		Type	rw							
$B4_H$	**MR2** **Reset: 00_H** MDU Result Register 2	Bit Field	DATA							
		Type	rh							
$B5_H$	**MD3** **Reset: 00_H** MDU Operand Register 3	Bit Field	DATA							
		Type	rw							
$B5_H$	**MR3** **Reset: 00_H** MDU Result Register 3	Bit Field	DATA							
		Type	rh							
$B6_H$	**MD4** **Reset: 00_H** MDU Operand Register 4	Bit Field	DATA							
		Type	rw							
$B6_H$	**MR4** **Reset: 00_H** MDU Result Register 4	Bit Field	DATA							
		Type	rh							
$B7_H$	**MD5** **Reset: 00_H** MDU Operand Register 5	Bit Field	DATA							
		Type	rw							
$B7_H$	**MR5** **Reset: 00_H** MDU Result Register 5	Bit Field	DATA							
		Type	rh							

3.2.4.3 CORDIC Registers

The CORDIC SFRs can be accessed in the mapped memory area (RMAP = 1).

Table 7 CORDIC Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 1										
$9A_H$	**CD_CORDXL** **Reset: 00_H** CORDIC X Data Low Byte	Bit Field	DATAL							
		Type	rw							
$9B_H$	**CD_CORDXH** **Reset: 00_H** CORDIC X Data High Byte	Bit Field	DATAH							
		Type	rw							
$9C_H$	**CD_CORDYL** **Reset: 00_H** CORDIC Y Data Low Byte	Bit Field	DATAL							
		Type	rw							
$9D_H$	**CD_CORDYH** **Reset: 00_H** CORDIC Y Data High Byte	Bit Field	DATAH							
		Type	rw							
$9E_H$	**CD_CORDZL** **Reset: 00_H** CORDIC Z Data Low Byte	Bit Field	DATAL							
		Type	rw							
$9F_H$	**CD_CORDZH** **Reset: 00_H** CORDIC Z Data High Byte	Bit Field	DATAH							
		Type	rw							

Table 11 ADC Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
$D3_H$	**ADC_RESR3H Reset: 00_H** Result Register 3 High	Bit Field	RESULT							
		Type	rh							
RMAP = 0, PAGE 3										
CA_H	**ADC_RESRA0L Reset: 00_H** Result Register 0, View A Low	Bit Field	RESULT			VF	DRC	CHNR		
		Type	rh			rh	rh	rh		
CB_H	**ADC_RESRA0H Reset: 00_H** Result Register 0, View A High	Bit Field	RESULT							
		Type	rh							
CC_H	**ADC_RESRA1L Reset: 00_H** Result Register 1, View A Low	Bit Field	RESULT			VF	DRC	CHNR		
		Type	rh			rh	rh	rh		
CD_H	**ADC_RESRA1H Reset: 00_H** Result Register 1, View A High	Bit Field	RESULT							
		Type	rh							
CE_H	**ADC_RESRA2L Reset: 00_H** Result Register 2, View A Low	Bit Field	RESULT			VF	DRC	CHNR		
		Type	rh			rh	rh	rh		
CF_H	**ADC_RESRA2H Reset: 00_H** Result Register 2, View A High	Bit Field	RESULT							
		Type	rh							
$D2_H$	**ADC_RESRA3L Reset: 00_H** Result Register 3, View A Low	Bit Field	RESULT			VF	DRC	CHNR		
		Type	rh			rh	rh	rh		
$D3_H$	**ADC_RESRA3H Reset: 00_H** Result Register 3, View A High	Bit Field	RESULT							
		Type	rh							
RMAP = 0, PAGE 4										
CA_H	**ADC_RCR0 Reset: 00_H** Result Control Register 0	Bit Field	VFCTR	WFR	0	IEN	0			DRCTR
		Type	rw	rw	r	rw	r			rw
CB_H	**ADC_RCR1 Reset: 00_H** Result Control Register 1	Bit Field	VFCTR	WFR	0	IEN	0			DRCTR
		Type	rw	rw	r	rw	r			rw
CC_H	**ADC_RCR2 Reset: 00_H** Result Control Register 2	Bit Field	VFCTR	WFR	0	IEN	0			DRCTR
		Type	rw	rw	r	rw	r			rw
CD_H	**ADC_RCR3 Reset: 00_H** Result Control Register 3	Bit Field	VFCTR	WFR	0	IEN	0			DRCTR
		Type	rw	rw	r	rw	r			rw
CE_H	**ADC_VFCR Reset: 00_H** Valid Flag Clear Register	Bit Field	0				VFC3	VFC2	VFC1	VFC0
		Type	r				w	w	w	w
RMAP = 0, PAGE 5										
CA_H	**ADC_CHINFR Reset: 00_H** Channel Interrupt Flag Register	Bit Field	CHINF7	CHINF6	CHINF5	CHINF4	CHINF3	CHINF2	CHINF1	CHINF0
		Type	rh	rh	rh	rh	rh	rh	rh	rh
CB_H	**ADC_CHINCR Reset: 00_H** Channel Interrupt Clear Register	Bit Field	CHINC7	CHINC6	CHINC5	CHINC4	CHINC3	CHINC2	CHINC1	CHINC0
		Type	w	w	w	w	w	w	w	w

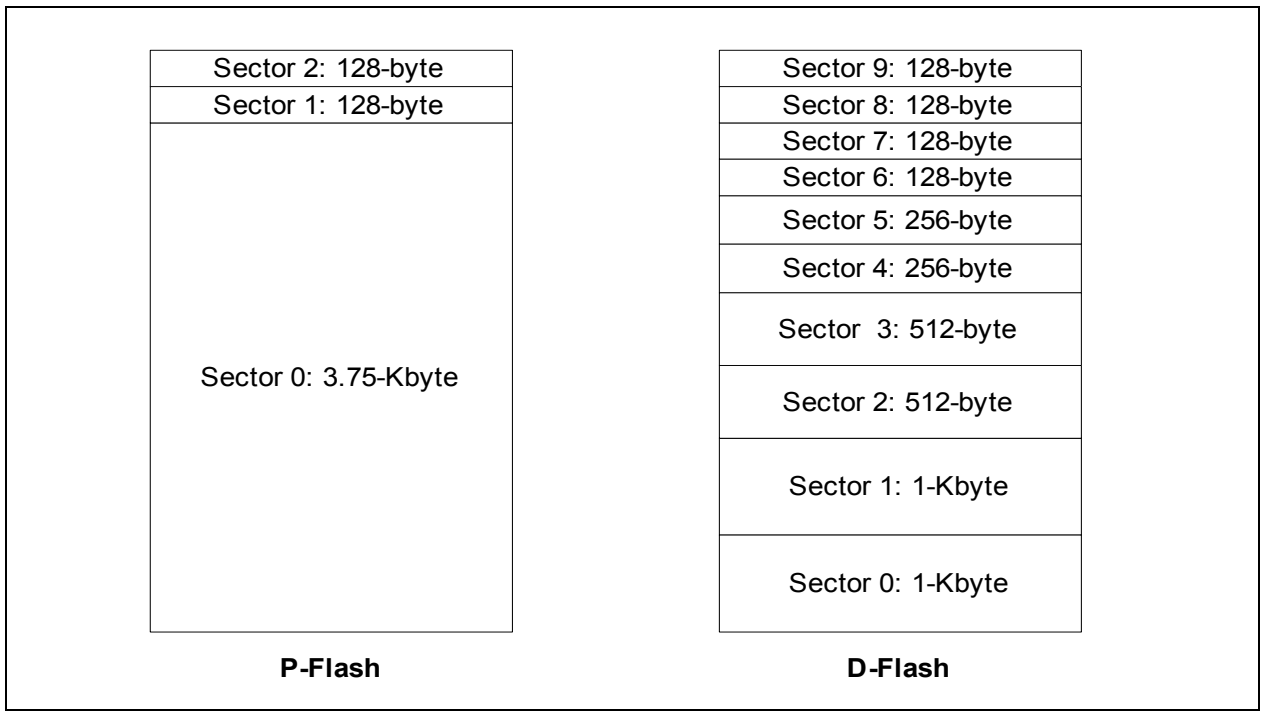


Figure 11 Flash Bank Sectorization

The internal structure of each Flash bank represents a sector architecture for flexible erase capability. The minimum erase width is always a complete sector, and sectors can be erased separately or in parallel. Contrary to standard EPROMs, erased Flash memory cells contain 0s.

The D-Flash bank is divided into more physical sectors for extended erasing and reprogramming capability; even numbers for each sector size are provided to allow greater flexibility and the ability to adapt to a wide range of application requirements.

3.3.2 Parallel Read Access of P-Flash

To enhance system performance, the P-Flash banks are configured for parallel read to allow two bytes of linear code to be read in 4 x CCLK cycles, compared to 6 x CCLK cycles if serial read is performed. This is achieved by reading two bytes in parallel from a P-Flash bank pair within the 3 x CCLK cycles access time and storing them in a cache. Subsequent read from the cache by the CPU does not require a wait state and can be completed within 1 x CCLK cycle. The result is the average instruction fetch time from the P-Flash banks is reduced and thus, the MIPS (Mega Instruction Per Second) of the system is increased.

However, if the parallel read feature is not desired due to certain timing constraints, it can be disabled by calling the parallel read disable subroutine.

3.3.3 Flash Programming Width

For the P-Flash banks, a programmed wordline (WL) must be erased before it can be reprogrammed as the Flash cells can only withstand one gate disturb. This means that the entire sector containing the WL must be erased since it is impossible to erase a single WL.

For the D-Flash bank, the same WL can be programmed twice before erasing is required as the Flash cells are able to withstand two gate disturbs. This means if the number of data bytes that needs to be written is smaller than the 32-byte minimum programming width, the user can opt to program this number of data bytes (x; where x can be any integer from 1 to 31) first and program the remaining bytes (32 - x) later. Hence, it is possible to program the same WL, for example, with 16 bytes of data two times (see **Figure 12**)

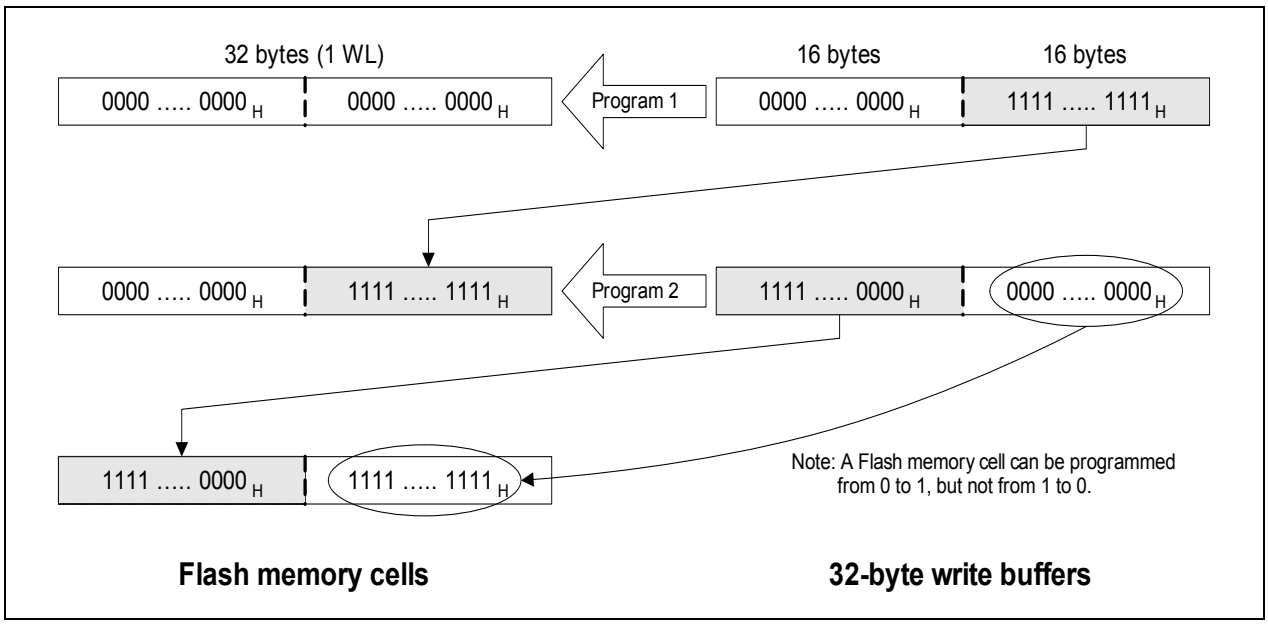


Figure 12 D-Flash Programming

Note: When programming a D-Flash WL the second time, the previously programmed Flash memory cells (whether 0s or 1s) should be reprogrammed with 0s to retain its original contents and to prevent "over-programming".

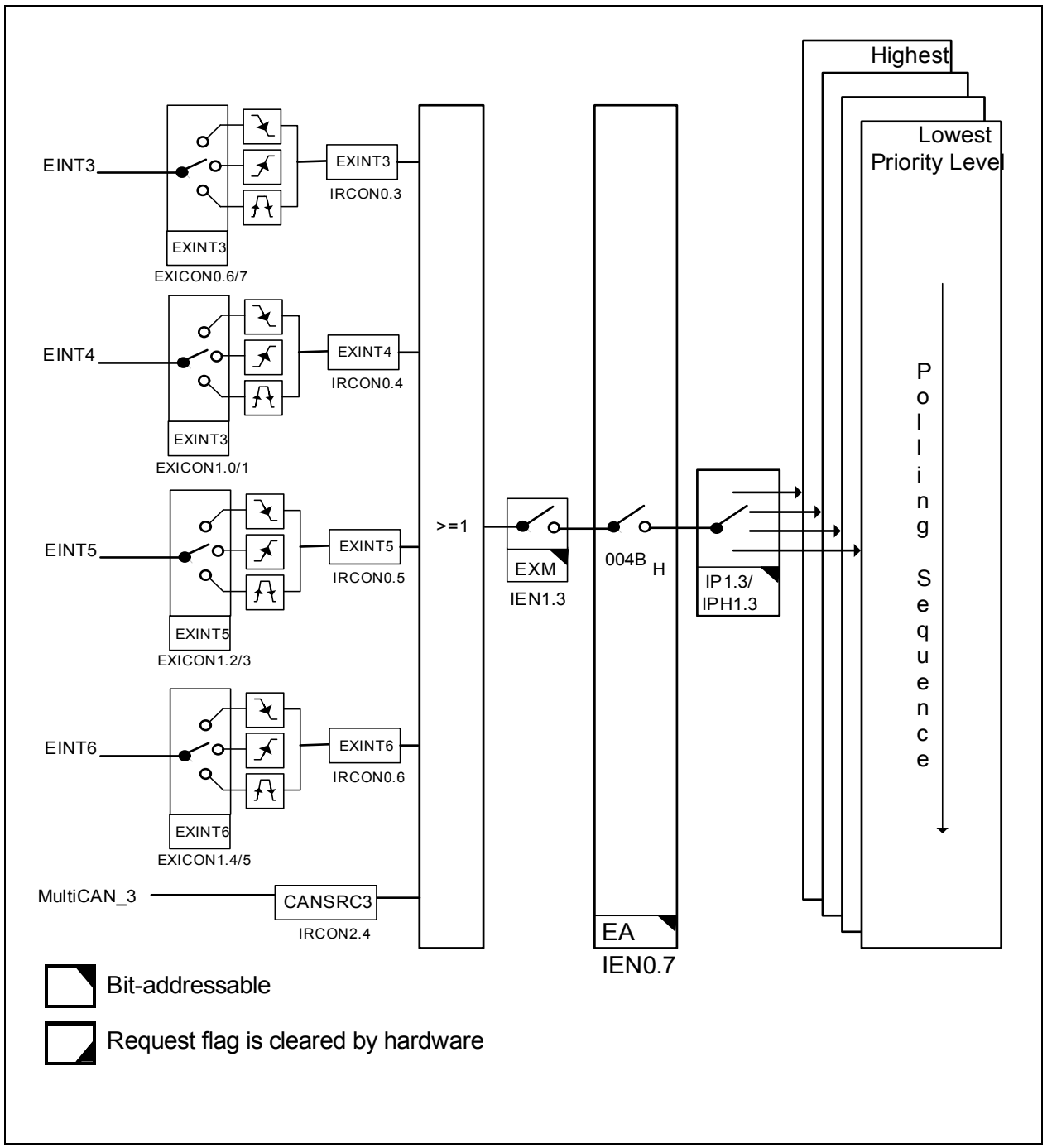


Figure 17 Interrupt Request Sources (Part 4)

3.4.2 Interrupt Source and Vector

Each interrupt event source has an associated interrupt vector address for the interrupt node it belongs to. This vector is accessed to service the corresponding interrupt node request. The interrupt service of each interrupt source can be individually enabled or disabled via an enable bit. The assignment of the XC886/888 interrupt sources to the interrupt vector address and the corresponding interrupt node enable bits are summarized in **Table 20**.

Table 20 Interrupt Vector Addresses

Interrupt Source	Vector Address	Assignment for XC886/888	Enable Bit	SFR
NMI	0073_H	Watchdog Timer NMI	NMIWDT	NMICON
		PLL NMI	NMIPLL	
		Flash NMI	NMIFLASH	
		VDDC Prewarning NMI	NMIVDD	
		VDDP Prewarning NMI	NMIVDDP	
		Flash ECC NMI	NMIECC	
XINTR0	0003_H	External Interrupt 0	EX0	IEN0
XINTR1	$000B_H$	Timer 0	ET0	
XINTR2	0013_H	External Interrupt 1	EX1	
XINTR3	$001B_H$	Timer 1	ET1	
XINTR4	0023_H	UART	ES	
XINTR5	$002B_H$	T2	ET2	
		UART Fractional Divider (Normal Divider Overflow)		
		MultiCAN Node 0		
		LIN		

Table 25 shows the VCO range for the XC886/888.

Table 25 VCO Range

f_{VCOmin}	f_{VCOmax}	$f_{VCOFREEmin}$	$f_{VCOFREEmax}$	Unit
150	200	20	80	MHz
100	150	10	80	MHz

3.8.1 Recommended External Oscillator Circuits

The oscillator circuit, a Pierce oscillator, is designed to work with both, an external crystal oscillator or an external stable clock source. It basically consists of an inverting amplifier and a feedback element with XTAL1 as input, and XTAL2 as output.

When using a crystal, a proper external oscillator circuitry must be connected to both pins, XTAL1 and XTAL2. The crystal frequency can be within the range of 4 MHz to 12 MHz. Additionally, it is necessary to have two load capacitances C_{X1} and C_{X2}, and depending on the crystal type, a series resistor R_{X2}, to limit the current. A test resistor R_Q may be temporarily inserted to measure the oscillation allowance (negative resistance) of the oscillator circuitry. R_Q values are typically specified by the crystal vendor. The C_{X1} and C_{X2} values shown in Figure 25 can be used as starting points for the negative resistance evaluation and for non-productive systems. The exact values and related operating range are dependent on the crystal frequency and have to be determined and optimized together with the crystal vendor using the negative resistance method. Oscillation measurement with the final target system is strongly recommended to verify the input amplitude at XTAL1 and to determine the actual oscillation allowance (margin negative resistance) for the oscillator-crystal system.

When using an external clock signal, the signal must be connected to XTAL1. XTAL2 is left open (unconnected).

The oscillator can also be used in combination with a ceramic resonator. The final circuitry must also be verified by the resonator vendor. Figure 25 shows the recommended external oscillator circuitries for both operating modes, external crystal mode and external input clock mode.

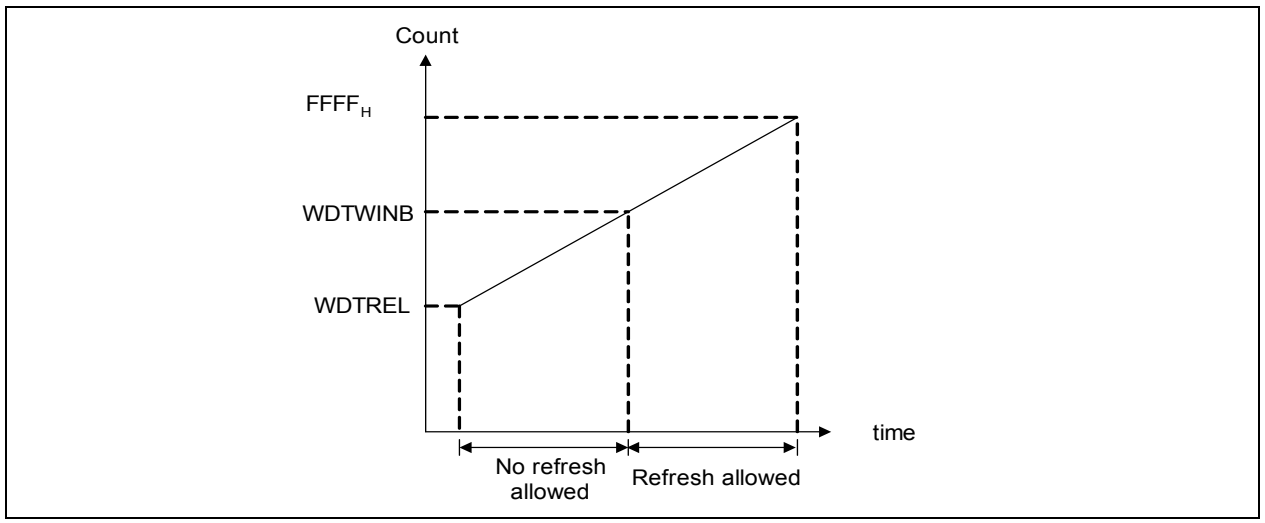


Figure 29 WDT Timing Diagram

Table 27 lists the possible watchdog time ranges that can be achieved using a certain module clock. Some numbers are rounded to 3 significant digits.

Table 27 Watchdog Time Ranges

Reload value In WDTREL	Prescaler for f_{PCLK}	
	2 (WDTIN = 0)	**128 (WDTIN = 1)**
	24 MHz	**24 MHz**
FF_H	21.3 µs	1.37 ms
$7F_H$	2.75 ms	176 ms
00_H	5.46 ms	350 ms

3.23 Chip Identification Number

The XC886/888 identity (ID) register is located at Page 1 of address $B3_H$. The value of ID register is 09_H for Flash devices and 22_H for ROM devices. However, for easy identification of product variants, the Chip Identification Number, which is an unique number assigned to each product variant, is available. The differentiation is based on the product, variant type and device step information.

Two methods are provided to read a device's chip identification number:

- In-application subroutine, GET_CHIP_INFO
- Bootstrap loader (BSL) mode A

Table 36 lists the chip identification numbers of available XC886/888 Flash and ROM device variants.

Table 36 Chip Identification Number

Product Variant	Chip Identification Number		
	AA-Step	AB-Step	AC-Step
Flash Devices			
XC886CLM-8FFA 3V3	-	09500102_H	$0B500102_H$
XC888CLM-8FFA 3V3	-	09500103_H	$0B500103_H$
XC886LM-8FFA 3V3	-	09500122_H	$0B500122_H$
XC888LM-8FFA 3V3	-	09500123_H	$0B500123_H$
XC886CLM-6FFA 3V3	-	09551502_H	$0B551502_H$
XC888CLM-6FFA 3V3	-	09551503_H	$0B551503_H$
XC886LM-6FFA 3V3	-	09551522_H	$0B551522_H$
XC888LM-6FFA 3V3	-	09551523_H	$0B551523_H$
XC886CM-8FFA 3V3	-	09580102_H	$0B580102_H$
XC888CM-8FFA 3V3	-	09580103_H	$0B580103_H$
XC886C-8FFA 3V3	-	09580142_H	$0B580142_H$
XC888C-8FFA 3V3	-	09580143_H	$0B580143_H$
XC886-8FFA 3V3	-	09580162_H	$0B580162_H$
XC888-8FFA 3V3	-	09580163_H	$0B580163_H$
XC886CM-6FFA 3V3	-	$095D1502_H$	$0B5D1502_H$
XC888CM-6FFA 3V3	-	$095D1503_H$	$0B5D1503_H$
XC886C-6FFA 3V3	-	$095D1542_H$	$0B5D1542_H$
XC888C-6FFA 3V3	-	$095D1543_H$	$0B5D1543_H$

4 Electrical Parameters

Chapter 4 provides the characteristics of the electrical parameters which are implementation-specific for the XC886/888.

4.1 General Parameters

The general parameters are described here to aid the users in interpreting the parameters mainly in **Section 4.2** and **Section 4.3**.

4.1.1 Parameter Interpretation

The parameters listed in this section represent partly the characteristics of the XC886/888 and partly its requirements on the system. To aid interpreting the parameters easily when evaluating them for a design, they are indicated by the abbreviations in the “Symbol” column:

- **CC**
  These parameters indicate **C**ontroller **C**haracteristics, which are distinctive features of the XC886/888 and must be regarded for a system design.
- **SR**
  These parameters indicate **S**ystem **R**equirements, which must be provided by the microcontroller system in which the XC886/888 is designed in.

Table 38 Input/Output Characteristics (Operating Conditions apply) (cont'd)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			min.	max.		
Input high voltage on RESET pin	V_{IHR}	SR	0.7 × V_{DDP}	–	V	CMOS Mode
Input high voltage on TMS pin	V_{IHT}	SR	0.75 × V_{DDP}	–	V	CMOS Mode
Input Hysteresis on port pins	$HYSP$	CC	0.07 × V_{DDP}	–	V	CMOS Mode[1)]
Input Hysteresis on XTAL1	$HYSX$	CC	0.07 × V_{DDC}	–	V	[1)]
Input low voltage at XTAL1	V_{ILX}	SR	V_{SS} - 0.5	0.3 × V_{DDC}	V	
Input high voltage at XTAL1	V_{IHX}	SR	0.7 × V_{DDC}	V_{DDC} + 0.5	V	
Pull-up current	I_{PU}	SR	–	-10	µA	$V_{IHP,min}$
			-150	–	µA	$V_{ILP,max}$
Pull-down current	I_{PD}	SR	–	10	µA	$V_{ILP,max}$
			150	–	µA	$V_{IHP,min}$
Input leakage current	I_{OZ1}	CC	-1	1	µA	$0 < V_{IN} < V_{DDP}$, $T_A \leq 125°C$[2)]
Input current at XTAL1	I_{ILX}	CC	-10	10	µA	
Overload current on any pin	I_{OV}	SR	-5	5	mA	
Absolute sum of overload currents	$\Sigma\|I_{OV}\|$	SR	–	25	mA	[3)]
Voltage on any pin during V_{DDP} power off	V_{PO}	SR	–	0.3	V	[4)]
Maximum current per pin (excluding V_{DDP} and V_{SS})	I_M SR	SR	–	15	mA	
Maximum current for all pins (excluding V_{DDP} and V_{SS})	$\Sigma\|I_M\|$	SR	–	90	mA	
Maximum current into V_{DDP}	I_{MVDDP}	SR	–	120	mA	[3)]

Table 44 Power Down Current (Operating Conditions apply; V_{DDP} = 3.3V range)

Parameter	Symbol	Limit Values		Unit	Test Condition
		typ.[1]	max.[2]		
V_{DDP} = 3.3V Range					
Power-Down Mode	I_{PDP}	1	10	µA	T_A = + 25 °C[3][4]
		-	30	µA	T_A = + 85 °C[4][5]

1) The typical I_{PDP} values are measured at V_{DDP} = 3.3 V.

2) The maximum I_{PDP} values are measured at V_{DDP} = 3.6 V.

3) I_{PDP} has a maximum value of 200 µA at T_A = + 125 °C.

4) I_{PDP} is measured with: $\overline{\text{RESET}}$ = V_{DDP}, V_{AGND}= V_{SS}, RXD/INT0 = V_{DDP}; rest of the ports are programmed to be input with either internal pull devices enabled or driven externally to ensure no floating inputs.

5) Not subjected to production test, verified by design/characterization.

4.3.3 Power-on Reset and PLL Timing

Table 49 provides the characteristics of the power-on reset and PLL timing in the XC886/888.

Table 46 Power-On Reset and PLL Timing (Operating Conditions apply)

Parameter	Symbol		Limit Values			Unit	Test Conditions
			min.	typ.	max.		
Pad operating voltage	V_{PAD}	CC	2.3	–	–	V	1)
On-Chip Oscillator start-up time	t_{OSCST}	CC	–	–	500	ns	1)
Flash initialization time	t_{FINIT}	CC	–	160	–	µs	1)
$\overline{\text{RESET}}$ hold time	t_{RST}	SR	–	500	–	µs	V_{DDP} rise time (10% – 90%) ≤ 500µs 1)2)
PLL lock-in in time	t_{LOCK}	CC	–	–	200	µs	1)
PLL accumulated jitter	D_P		–	–	0.7	ns	1)3)

1) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

2) $\overline{\text{RESET}}$ signal has to be active (low) until V_{DDC} has reached 90% of its maximum value (typ. 2.5 V).

3) PLL lock at 96 MHz using a 4 MHz external oscillator. The PLL Divider settings are K = 2, N = 48 and P = 1.

4.3.7 SSC Master Mode Timing

Table 51 provides the characteristics of the SSC timing in the XC886/888.

Table 51 SSC Master Mode Timing (Operating Conditions apply; CL = 50 pF)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			min.	max.		
SCLK clock period	t_0	CC	$2*T_{SSC}$	–	ns	1)2)
MTSR delay from SCLK ↓	t_1	CC	0	8	ns	2)
MRST setup to SCLK ↓	t_2	SR	24	–	ns	2)
MRST hold from SCLK ↓	t_3	SR	0	–	ns	2)

1) $T_{SSCmin} = T_{CPU} = 1/f_{CPU}$. When f_{CPU} = 24 MHz, t_0 = 83.3ns. T_{CPU} is the CPU clock period.

2) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

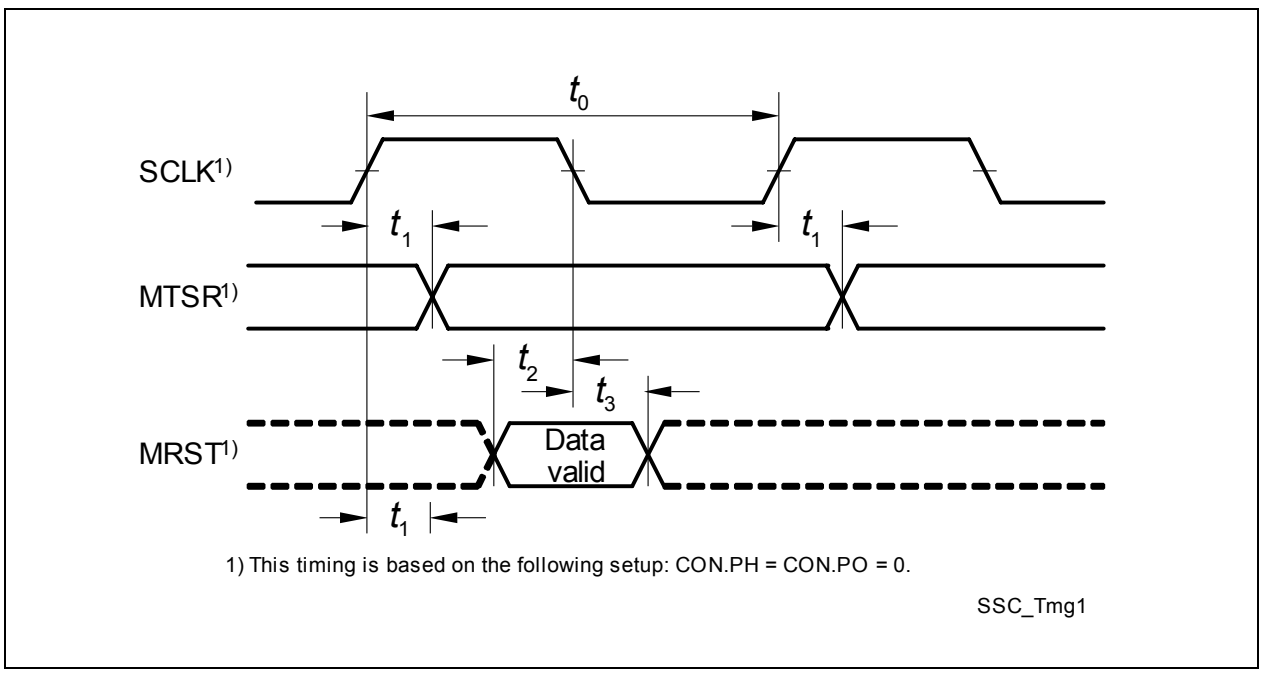


Figure 52 SSC Master Mode Timing

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